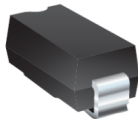


# MATERIAL DECLARATION SHEET



Material Number	SMA6J Series			
Product Line	Semiconductor Products			
Compliance Date	2019/04/25			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	0.002198	Silicon	7440-21-3	60.18	2.0925	3.4769
				Phosphorus	7723-14-0	0.01	0.0003	
				Boron	7440-42-8	0.01	0.0003	
				Nickel	7440-02-0	14.8	0.5146	
				Lead	7439-92-1	12.5	0.4346	
				Silicon dioxide	7631-86-9	10.0	0.3477	
				Aluminum oxide	1344-28-1	2.5	0.0869	
2	High-melting point Solder paste	Solder paste	0.002063	Tin	7440-31-5	5	0.1632	3.2636
				Lead	7439-92-1	92.5	3.0188	
				Silver	7440-22-4	2.5	0.0816	
3	Lead frame	Copper	0.0275	Copper	7440-50-8	99.8	43.416	43.5031
				Iron	7439-89-6	0.15	0.0653	
				Phosphorus	7723-14-0	0.05	0.0218	
4	Molding compound	Epoxy material	0.03079	Silica	14808-60-7	76	37.0177	48.7076
				Epoxy resin	25928-94-3	9	4.3837	
				Phenolic resin-A,B	9003-35-4	8	3.8966	
				Hydroxide metal	21645-51-2	6	2.9225	
				Carbon black	1333-86-4	1	0.4871	
5	Plating	Matte-100% tin	0.000663	Tin	7440-315	100	1.0488	1.0488
		Total weight	0.063214					

# MATERIAL DECLARATION SHEET



This Document was updated on: 2018/08/02

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
3. 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.